



Ph.D. Heejin Lee

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Heejin Lee, Ph.D. has been Team Leader at SK Hynix since 2019 in charge of package design for the DRAM, Nand and Controller package.

Prior to joining SK Hynix Company, Lee was Principal Engineer for Samsung Electronics Company. During his 14 years at Samsung Electronics Company, Lee spent time doing responsibility of package product development, design and simulation.

Lee received a Ph.D. degree in mechanical engineering from University of Michigan, Ann Arbor, Michigan, USA and a master degree in mechanical engineering from the Seoul National University, Seoul, Korea.